



## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT I - PCN # : A1911-01

**PCN Type:** Assembly Process  
**Data Sheet Change:** None  
 No change in moisture sensitivity level (MSL)

**Detail Of Change:**

This notification is to advise our customers that IDT is adding 2D barcode on the product marking to improve traceability. The 2D barcode contains wafer and substrate information.

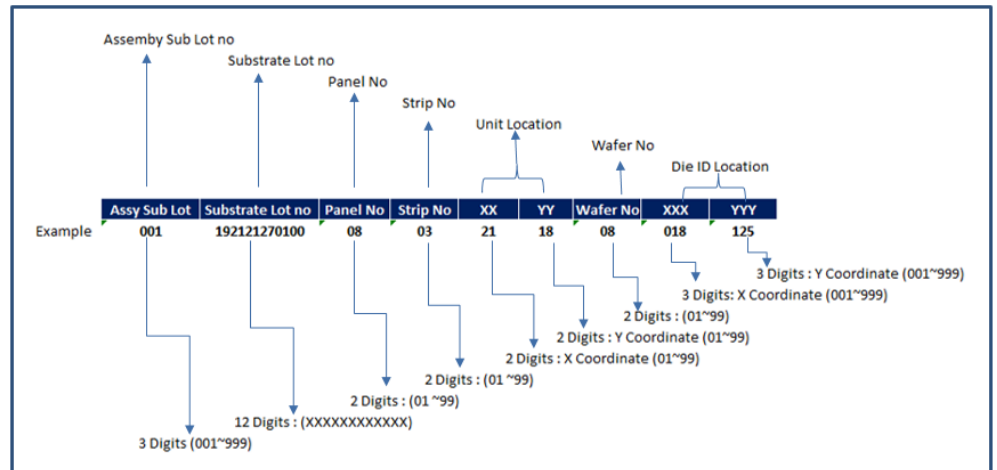
There is no change to the moisture performance.

### 2D Barcode Information

RCD: 13.5 x 8.0 mm



DB: 7.5 x 3.0 mm

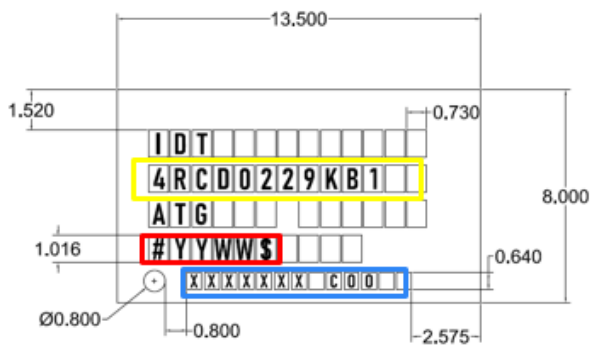


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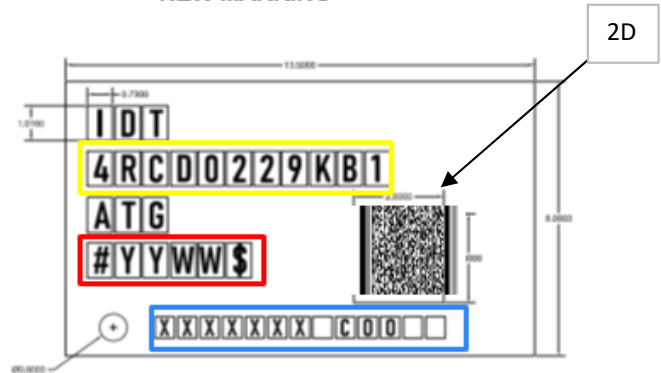
### ATTACHMENT I - PCN # : A1911-01

## DDR4 RCD Marking Format and Dimension

CURRENT MARKING



NEW MARKING



**4RCD0229KB1**

Device info – Line 2

**#YYWW\$**

Device step , 4<sup>th</sup> line “#”  
Subcon location 4<sup>th</sup> line “\$”  
Date code is YYWW – 4<sup>th</sup> line

**XXXXXXXXXXC000**

Assembly lot no. – last line beside pin 1

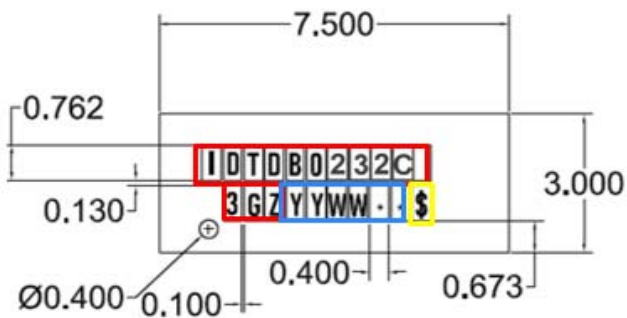
- Fixed Substrate level 2D ID Content
  - 17 digit max
  - Lot no (12) + PP + SS
- Combine Sublot + Substrate 2D ID info + Unit code + wafer and die ID and mark into IDT Unit
  - Total 31 digits
  - Assembly Sublot (3)
  - substrate Lot no (12)
  - Panel No PP(2)
  - Strip No SS(2)
  - Unit Location , XXY(4)
  - Wafer ID WW(2)
  - Die Location XXXYYY (6)

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT I - PCN # : A1911-01

## DDR4 DB Marking Format and Dimension

### CURRENT MARKING



**IDTDB0232**

**C3GZ**

Device info is on line 1 & 2  
Device Step is on line 2 "Z"

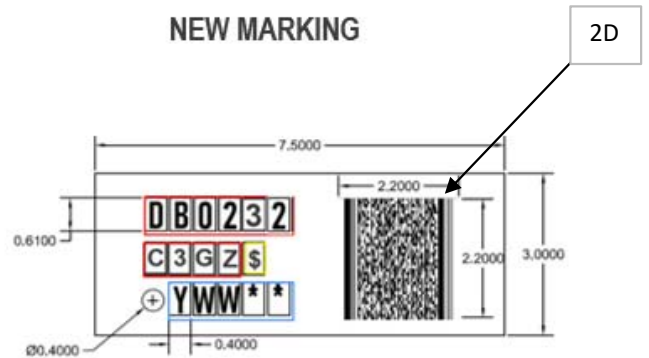
**\$**

Last character of line 2, "\$", subcon location

**YWW\*\***

3<sup>rd</sup> line, YWW, Date code  
Assembly lot no 3rd line "\*\*\*" – Lot Sequential code.

### NEW MARKING



- Fixed Substrate level 2D ID Content
  - 17 digit max
  - Lot no (12) + PP + SS
- Combine Sublot + Substrate 2D ID info + Unit code + wafer and die ID and mark into IDT Unit
  - Total 31 digits
  - Assembly Sublot (3)
  - substrate Lot no (12)
  - Panel No PP(2)
  - Strip No SS(2)
  - Unit Location, XXYY(4)
  - Wafer ID WW(2)
  - Die Location XXXYYY (6)

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT II - PCN # : A1911-01

#### Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
4DB0124KB0AVG8	4DB0232KC1AAVG	4RCD0124KC0ATGI	4RCD0232HDKC1ATG
4DB0124KB1AVG8/M	4DB0232KC1AAVG8	4RCD0124KC0ATGI8	4RCD0232HDKC1ATG8
4DB0226EMKB0AVG	4DB0232KC1AVG	4RCD0229EMKB1ATG	4RCD0232KC0ATG
4DB0226EMKB0AVG8	4DB0232KC1AVG/M	4RCD0229EMKB1ATG8	4RCD0232KC0ATG/M
4DB0226KA3AVG	4DB0232KC1AVG8	4RCD0229KB0ATG	4RCD0232KC0ATG8
4DB0226KA3AVG/M	4DB0232KC1AVG8/M	4RCD0229KB0ATG8	4RCD0232KC0ATG8/M
4DB0226KA3AVG8	4DB0232KC2AAVG	4RCD0229KB1ATG	4RCD0232KC1ATG
4DB0226KA3AVG8/M	4DB0232KC2AAVG8	4RCD0229KB1ATG/M	4RCD0232KC1ATG/M
4DB0226KB0AAVG	4DB0232KC2AVG	4RCD0229KB1ATG8	4RCD0232KC1ATG8
4DB0226KB0AVG	4DB0232KC2AVG/M	4RCD0229KB1ATG8/B	4RCD0232KC1ATG8/B
4DB0226KB0AVG/M	4DB0232KC2AVG8	4RCD0229KB1ATG8/M	4RCD0232KC1ATG8/M
4DB0226KB0AVG8	4DB0232KC2AVG8/M	4RCD0229KB1MATG	4RCD0232KC1ATGI
4DB0226KB0AVG8/M	4DB0232KD0AVG	4RCD0229KB1MATG8	4RCD0232KC1ATGI/M
4DB0226KB0BAVG	4DB0232KD0AVG8	4RCD0232EMKC0ATG	4RCD0232KC1ATGI8
4DB0226KB0MAVG	4DB0232KD1AVG	4RCD0232EMKC0ATG8	4RCD0232KC1ATGI8/M
4DB0226KB0MAVG8	4DB0232KD1AVG8	4RCD0232EMKC1ATG	4RCD0299EMKB1ATG
4DB0232EMKD1AVG	4RCD0124KC0ATG	4RCD0232EMKC1ATG/B	4RCD0299EMKB1ATG8
4DB0232EMKD1AVG8	4RCD0124KC0ATG8	4RCD0232EMKC1ATG8	
4DB0232KC0AVG	4RCD0124KC0ATG8/B	4RCD0232EMKC1ATG8/	
4DB0232KC0AVG8	4RCD0124KC0ATG8/M	4RCD0232EMKC1ATG8B	